

RFM Integrated Device, Inc.

PRODUCT SPECIFICATION

Part Number: XTC4004

TCXO,32.768 KHz, +/- 1.5 ppm max @ 25°C +/- 3°C

SMD 3.2x2.5 32.768KHz TCXO

Features:

Miniature SMD Package



Description and Applications:

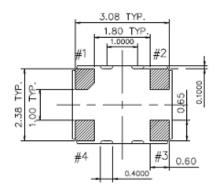
Surface mount 3.2mmx2.5mmm TCXO

Electrical Specifications:

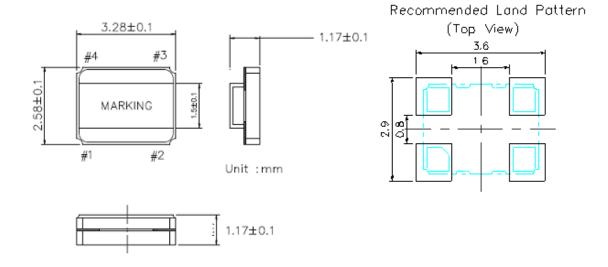
| XTC4004 | Specifications | | | | | | |
|---|---|--|--|--|--|--|--|
| Nominal Frequency, Fo | 32.768 KHz | | | | | | |
| Storage Temperature Range | -55°C to +85°C | | | | | | |
| Operating Temperature Range | -40°C to +85°C | | | | | | |
| Power Supply Voltage, Vdd | 3.3V +/- 5% | | | | | | |
| Output Waveform | CMOS Square Wave | | | | | | |
| Output Load | 15pF | | | | | | |
| "0" Level "1" Level | 0.4V max IoL=0.1mA Vdd-0.4V min Ioн=-0.1mA | | | | | | |
| Power Supply Current, Icc | 1uA typical 2uA max without load | | | | | | |
| Initial Frequency Tolerance | +/- 1.5 ppm max @ 25°C +/- 3°C | | | | | | |
| Duty Cycle | 40% ~ 60% Typical | | | | | | |
| Rise Time (20% -> 80% of final RF level in Vp-p) Fall Time (80% -> 20% of final RF level in Vp-p) | 100 nsec max. 100 nsec max. | | | | | | |
| Frequency Stability | | | | | | | |
| a. Vs. Temperature (-40~85°C) | +/- 5 ppm | | | | | | |
| b. Vs. Load varied 15pF +/-10% | +/- 0.2 ppm | | | | | | |
| c. Vs. Supply Voltage Delta Freq/V | +/- 1 ppm/V | | | | | | |
| | +/-0.432 sec/day max per day | | | | | | |
| Timing error over time | +/-12.960 sec/month max per month | | | | | | |
| | +/-2.628 min/year max per year | | | | | | |
| Supply Voltage Variation | 0.25 V max | | | | | | |
| Reflow | +/-1 ppm max | | | | | | |
| Start –Up Time | 1 s max @ 25°C, 3 s max over-40°C to +85°C | | | | | | |
| Aging | +/-3 ppm per years | | | | | | |

| Tri-State | |
|--|-------------|
| Enable Voltage (High) | 80% Vdd min |
| Disable Voltage (Low) output Tri-state | 20% Vdd max |
| Open | Forbidden |

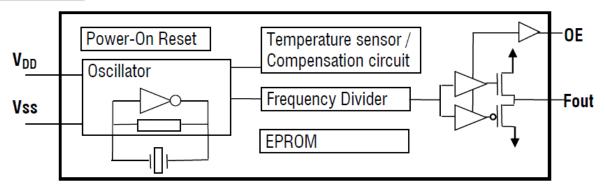
Mechanical Dimensions (mm):



| Pin 1 | Output Enable |
|-------|----------------|
| Pin 2 | Ground |
| Pin 3 | Frequency out |
| Pin 4 | Supply Voltage |

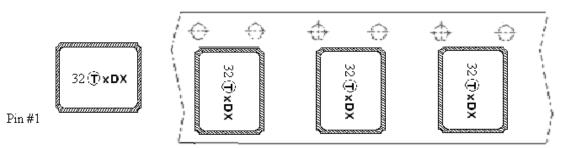


Block Diagram



Marking:

Line 1: 32 + Logo + Product Code + Date Code + Traceability code (1 or 2 letters)



Product Code Table

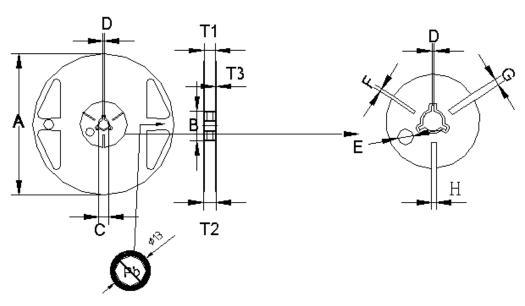
| Year | 2005 | 2006 | 2007 | 2008 |
|--------------|------|------|------|------|
| | 2009 | 2010 | 2011 | 2012 |
| | 2013 | 2014 | 2015 | 2016 |
| Product Code | X | х | X | X |

Date Code Table

| Date Co | Date Code Table | | | | | | | | | | | | | |
|---------|-----------------|------|------|------|------|------|------|------|------|------|------|------|--|--|
| WK01 | WK02 | WK03 | WK04 | WK05 | WK06 | WK07 | WK08 | WK09 | WK10 | WK11 | WK12 | WK13 | | |
| Α | В | С | D | E | F | G | Н | I | J | K | L | М | | |
| WK14 | WK15 | WK16 | WK17 | WK18 | WK19 | WK20 | WK21 | WK22 | WK23 | WK24 | WK25 | WK26 | | |
| N | 0 | Р | Q | R | S | Т | U | ν | W | Х | Y | Z | | |
| WK27 | WK28 | WK29 | WK30 | WK31 | WK32 | WK33 | WK34 | WK35 | WK36 | WK37 | WK38 | WK39 | | |
| a | b | С | d | e | f | g | h | i | j | k | I | m | | |
| WK40 | WK41 | WK42 | WK43 | WK44 | WK45 | WK46 | WK47 | WK48 | WK49 | WK50 | WK51 | WK52 | | |
| n | 0 | р | q | r | s | t | u | ν | w | х | У | Z | | |

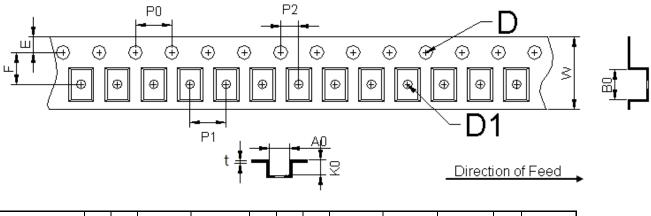
Packing (mm):

1. Reel Dimension



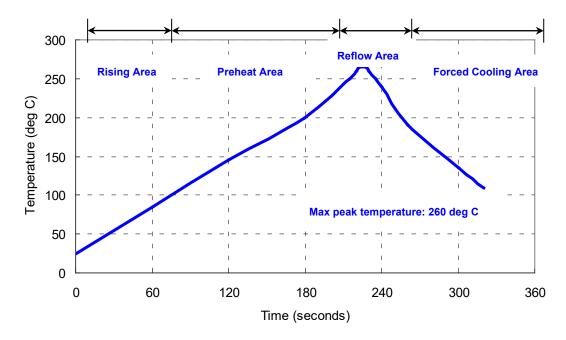
| | Α | В | С | D | E | F | Н | G | T2 | T1 | Т3 |
|------------|------|------|------|------|------|------|------|------|------|------|------|
| Dimensions | 180 | 60 | 13.0 | 2.0 | 9.1 | 2.9 | 3.9 | 4.9 | 11.4 | 9.0 | 1.2 |
| Tolerance | ±1.0 | +1.0 | ±0.2 | ±0.5 | ±0.5 | ±0.5 | ±0.5 | ±0.5 | ±1.0 | ±0.3 | ±0.1 |

2. Tape Dimension



| Unit: mm | A0 | В0 | W | F | Е | P0 | P1 | P2 | D1 | D | K0 | t |
|-----------|------|------|-----------|-------|------|------|------|-------|------------|-------------|------|-------|
| Dimension | 2.80 | 3.71 | 8.00 | 3.5 | 1.75 | 4.00 | 4.00 | 2 | 1.50 | 1.0 | 1.75 | 0.25 |
| Tolerance | ±0.1 | ±0.1 | +0.3/-0.1 | ±0.05 | ±0.1 | ±0.1 | ±0.1 | ±0.05 | +0.1/-0.00 | +0.25/-0.00 | ±0.1 | ±0.02 |

Reflow Profile:



Notes of the Usage:

- 1. Touch the solder iron at 260+/-5 deg C onto the leads for 10+/-2 sec max or touch the solder at 350+/-5 deg C onto the leads for 3+/-0.5 sec.
- 2. In the customer's reflow process, if it will remain some mechanical stress at the soldering terminals, also make some cracks on the soldering termination. Some cracks will cause open or short circuit and cause of thermal increasing or smoking. Don't make any excess mechanical stress to soldering points.
- 3. In case of giving a heavy shock to the products, it may make an open or short circuit and cause of thermal increasing and smoking. To avoid heavy shock impact applying to products is strictly required.

Notes of the Storage:

- 1. To keep products under the condition at the room temperature (-5~35 deg C) with normal humidity (45~75%). Absorption of moisture and dewdrop may make inferiority of characteristics and a short circuit.
- 2. Oxidization of terminals shall make the solderability more inferior. Dusts and corrosive gas will make a cause of the open or short circuit. Keep it in the clean place where is not in dusty and no corrosive gas.
- 3. Use the unti-static material to the storage package.
- 4. Don't put any excess weight to the VCTCXO in the storage process.